

REMARKS

Claims 1-8 remain in the application. Reconsideration of the rejections and objections at an early date is requested.

The examiner objected to the drawings, stating that Figs. 1 and 2 should be designated as "Prior Art." Replacement drawing sheets in compliance with this requirement are submitted herewith.

The examiner requested that headings be included in the specification. The amendments to the specification are responsive to this request.

Claim 1 has been amended to more clearly state that the adhesive parts 14 are made of an *elastic* material, are applied at points and are cured prior to installing the chip modules 16. Analogous amendments have been introduced in Claim 7, which also has been corrected for an obvious omission concerning the antenna having antenna connections.

Claims 1 – 7 were rejected under 35 U.S.C. 102(b) as being anticipated by Ghaem et al. (U.S. Patent No. 6,161,761). Ghaem et al. discloses a smart card having a card body with at least one recess arranged therein for receiving at least one chip module. Embedded in the card body there is also a conductive structure body which has body contact connections, this conductive structure body being in particular an antenna having antenna connections. A first difference is that the antenna connections in general do not seem to be arranged below the edge region of the chip module in Ghaem et al. Also, the connecting means 42 of Ghaem et al., which are said to correspond to the module connections 17 of the present patent application, do not belong to IC Chip 38, but are rather to be considered to form part of substrate 40, such as is for example specified in column 6, line 35; column 6, lines 51 – 53; column 8, line 39; and column 9 lines 18 - 21, as well as several other passages of the description. Perhaps the most important difference which distinguishes the claimed subject matter over Ghaem et al. resides in the fact that the adhesive parts 14 of the present patent application are not only of conductive material but are made of elastic material, are applied at points, are cured prior to installing the chip module, with pressure being applied to produce an electric contact between the body contact connections 13

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and the module connections 17. On the contrary, the smart card device of Ghaem et al. seems to be produced by one of the two methods which are in summary introduced in pages 2 and 3 of the present patent application. This in particular means that the adhesive used in the device of Ghaem et al. is conductive thermoplastic or liquid adhesive, which is arranged on the ends 34 of the loop antenna 24 and on which is then placed the integrated circuit component 38 with the traces 42 of the substrate 40, and which is then subsequently cured in order to form an electrical and mechanical connection between the loop antenna and the substrate. This is stated in more detail in the passage cited also by the examiner on column 6 lines 20 - 58 of Ghaem et al. In particular column 6, lines 51 – 53, confirms that it is an electrical and mechanical connection which is established. These kinds of devices, however, have the drawbacks enumerated in the present application, in particular for example as set forth on page 2, last paragraph, of the application. In particular, the mechanical connection between the chip module and the card body by said adhesive results, in the event of frequent banding stresses, in loosening of the electrical connections.

Contrary to Graem et al., the present invention uses not only conductive, but also elastic adhesive, which is, moreover, applied only at points without filling up the whole volume of the cutout before installing the chip module. Moreover, the elastic adhesive parts are cured prior to installing the chip module and therefore do not form a mechanical connection to the latter by its adhesive force. It is only after installation of the chip module 16, which compresses the point-like applied adhesive parts 14, forming a kind of bumps, that the electrical connection between the module connection 17 and the body contact connections 13 are realized by pressure being applied by the inserted chip module 16 on the elastic adhesive part 14. This approach solves the problem of loosening electrical connections during frequent bending stresses, due to the fact that no mechanical connection has been established by an adhesive force, but only by the pressure being applied by the chip module onto the adhesive parts 40. Since in Ghaem et al. there is no indication that the adhesive is, in addition to its conductive properties, also elastic or should be applied in a pointwise manner or should be cured before insertion of the IC Card, it is believed that the claimed device is clearly novel.

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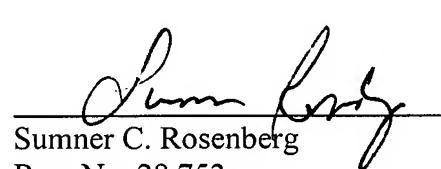
Based on the distinctions set forth above, both independent claim 1 and independent claim 7 should be allowable. Furthermore, claims 2 – 6 and 8 are allowable as dependent claims. Therefore, it is respectfully submitted that the examiner should pass this application to allowance.

It is noted that the examiner indicated that claim 8 would be allowable if amended to include the limitations of the claims on which it depends. Since the applicants believe that the above arguments overcome the novelty rejection, they decline to so amend claim 8 at this time.

No fees are believed due. If, however, the Commissioner believes any additional fees are due, the Commissioner is hereby authorized to charge any such fee deficiency, or credit any fee overpayment, to Deposit Account No. 14-0629.

Respectfully submitted,

NEEDLE & ROSENBERG, P.C.



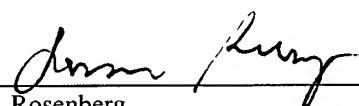
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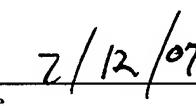
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